



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

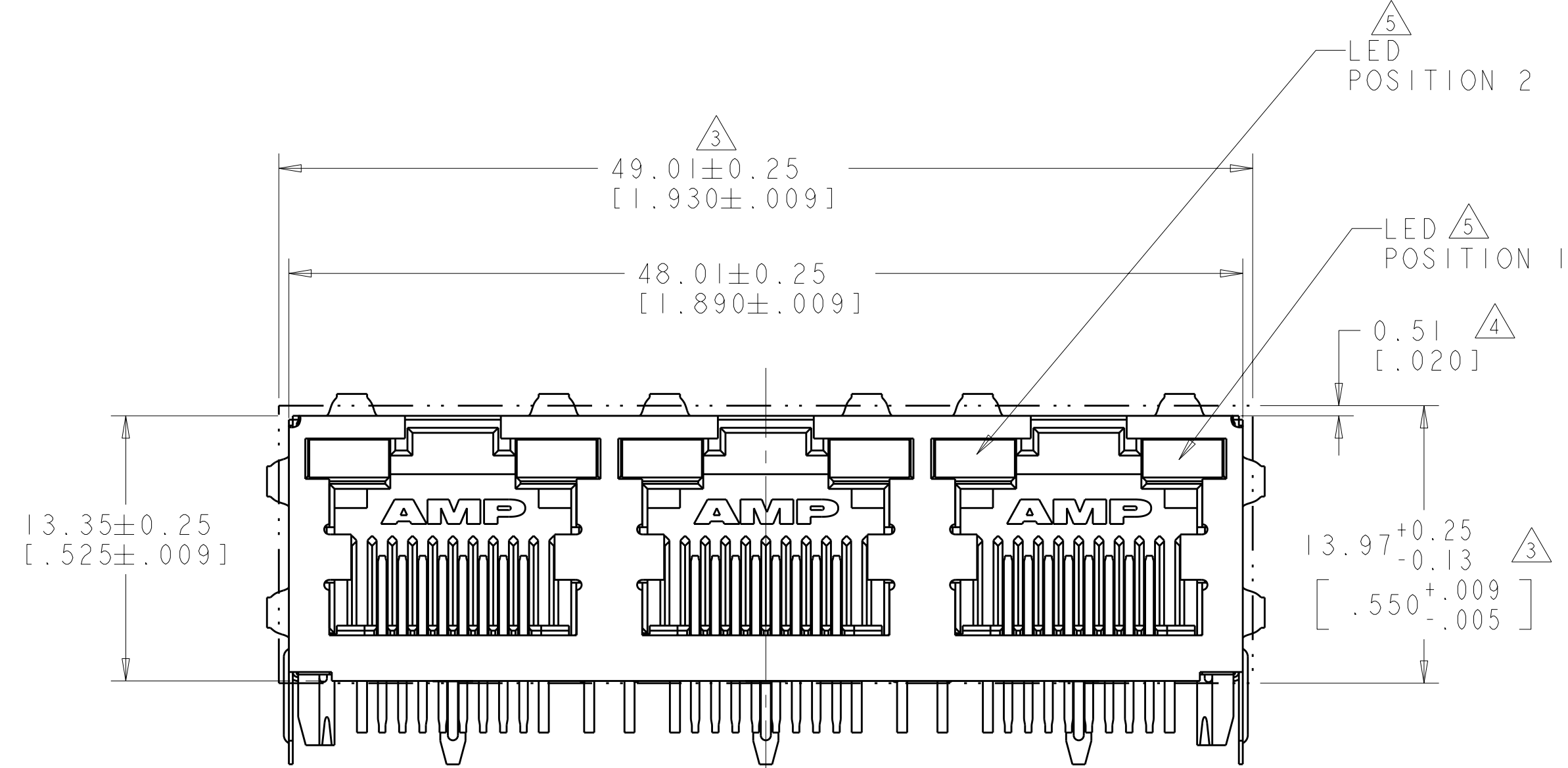
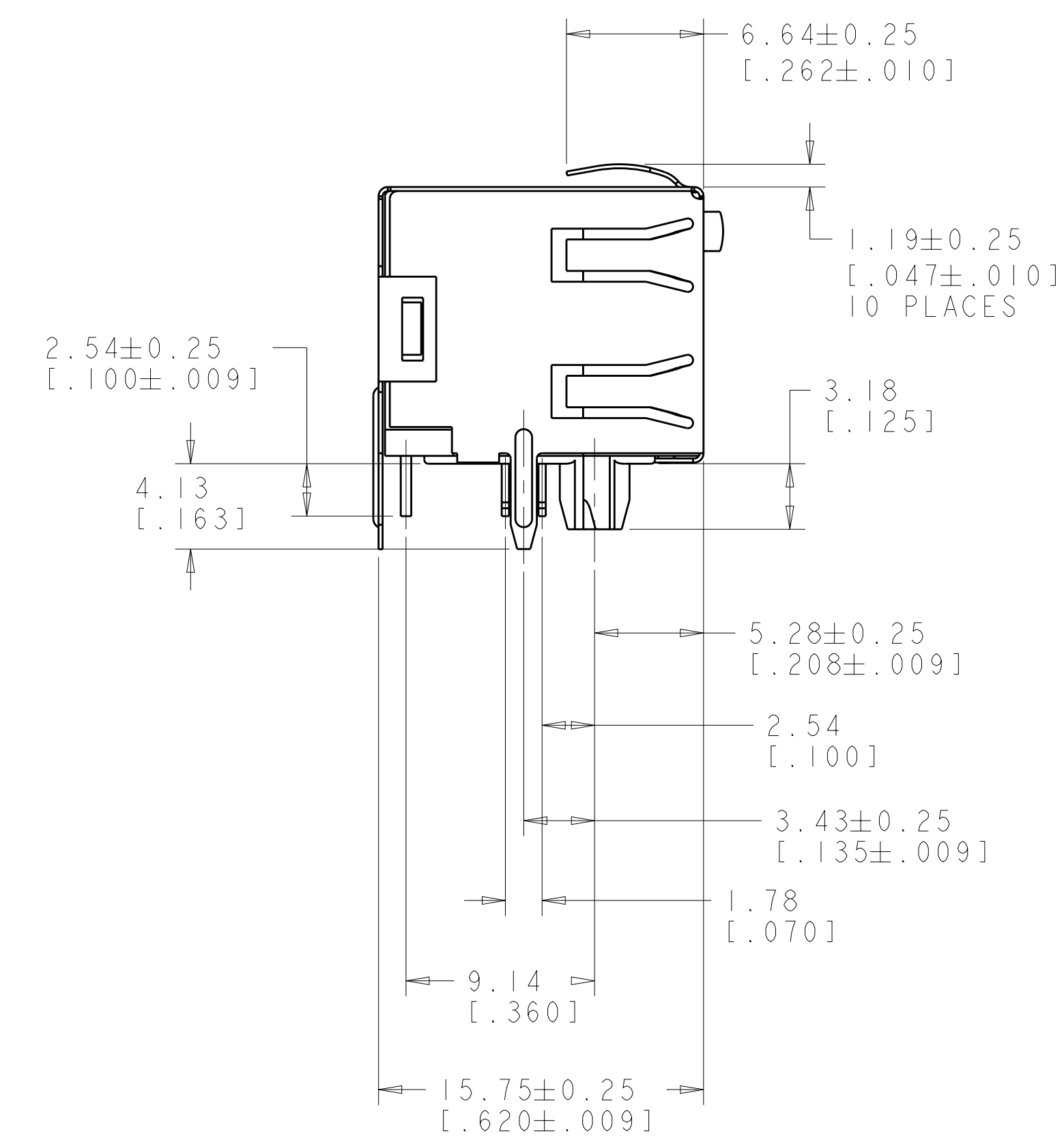
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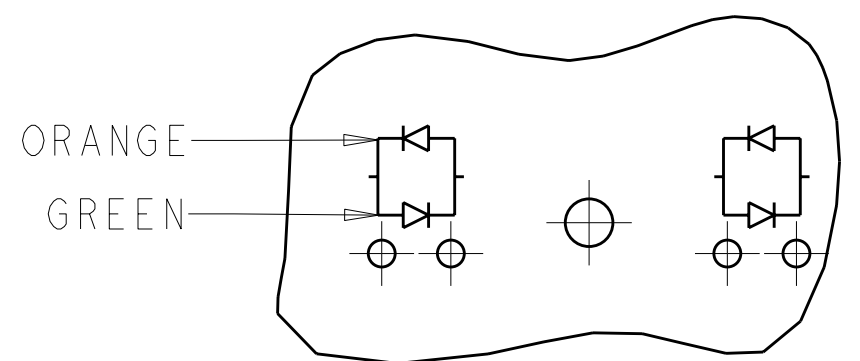
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



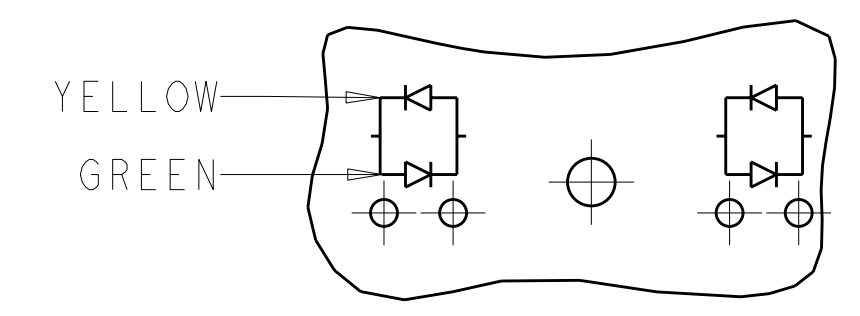
LOC	DIST	REV	DATE	BY	CHK	APPD
AA	00					
C		ECO-07-022131	02NOV07	LAM	JW	
C1		REVISED PER ECO-09-025699	11DEC09	WK	AEQ	



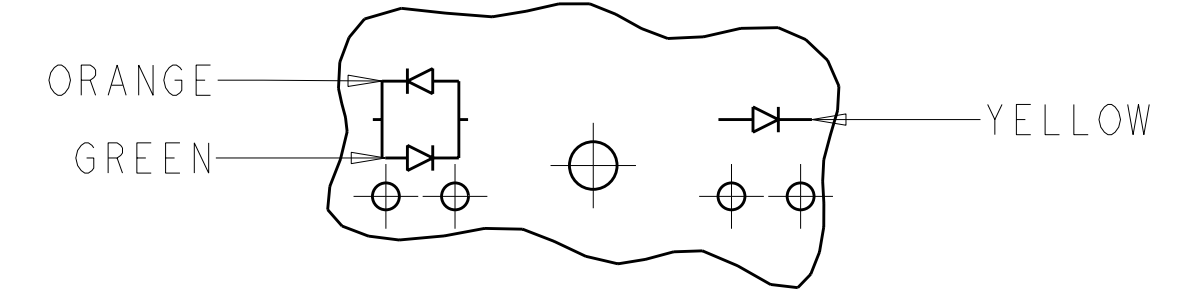
- MATERIAL: HOUSING - THERMOPLASTIC, BLACK, UL94V-0. TERMINALS - .36[.014] THICK PHOSPHOR BRONZE PLATED WITH 3.81µm [.000150] MINIMUM THICK BRIGHT TIN-LEAD IN SOLDER AREA, 1.27µm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [.000050] MINIMUM THICK NICKEL. SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY, PREPLATED WITH 1.27µm [.000050] MINIMUM SATIN NICKEL WITH 2.03µm [.000080] MINIMUM TIN POST DIPPED ON PCB TABS. LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS 0.51 X 0.51 [.020 X .020] CARBON STEEL WIREFRAME LEADS PLATED WITH 8.89µm [.000350] TIN/COPPER OVER 2.03µm [.000080] SILVER OVER 1.02µm [.000040] NICKEL UNDERPLATE OVER 2.03µm [.000080] COPPER UNDERPLATE.
  - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.  
 △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP OF PANEL OPENING.  
 △ SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.  
 6. THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.  
 △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI



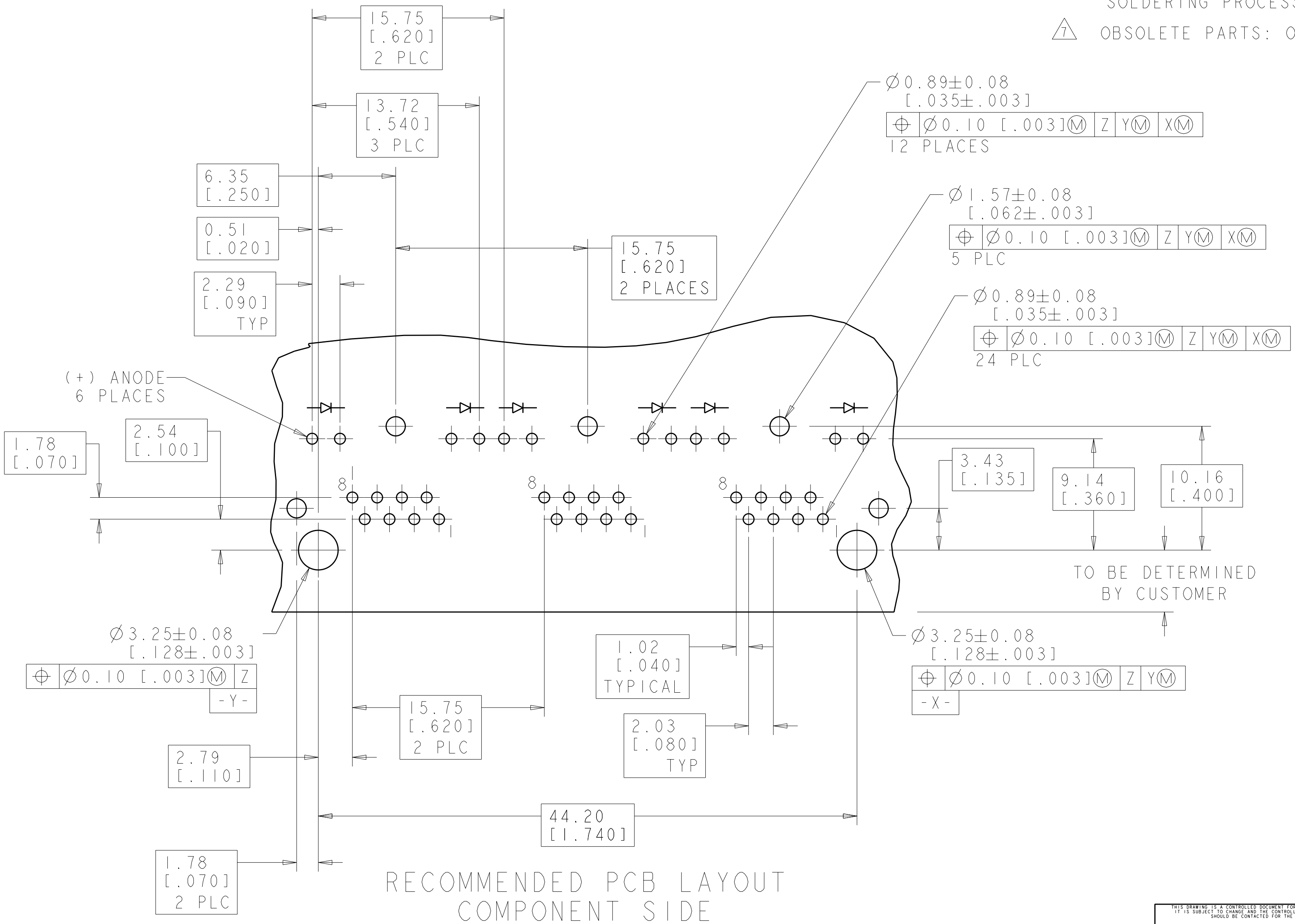
LED CURRENT DIAGRAM  
1116132-7 ONLY



LED CURRENT DIAGRAM  
1116132-8 ONLY



LED CURRENT DIAGRAM  
1116132-9 ONLY  
OBSOLETE



RECOMMENDED PCB LAYOUT  
COMPONENT SIDE

INDICATOR COLOR	POSITION 2	POSITION 1	PART NUMBER
<del>OBSOLETE</del> ORANGE/GREEN	YELLOW		1116132-9
YELLOW/GREEN	YELLOW/GREEN		1116132-8
<del>OBSOLETE</del> ORANGE/GREEN	ORANGE/GREEN		1116132-7
YELLOW	YELLOW		1116132-6
GREEN	GREEN		1116132-5
GREEN	YELLOW		1116132-4
<del>OBSOLETE</del> YELLOW	-		1116132-3
<del>OBSOLETE</del>	GREEN		1116132-2
YELLOW	GREEN		1116132-1

DIMENSIONS: mm [INCH]		TOLERANCES UNLESS OTHERWISE SPECIFIED: 9 PLC ± 5 PLC ±0.13(.005) 4 PLC ± ANGLES ±1°		DWN J. AHERON 29JUL98 CHK J. WESTMAN 13OCT07 APVD E. LAUBER 29JUL98		Tyco Electronics Tyco Electronics Corporation Harrisburg, PA 17105-3608	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		PRODUCT SPEC 108-1163-4 APPLICATION SPEC 114-2154		NAME INVERTED MODULAR JACK ASSEMBLY, 1 X 3, SHIELDED, PANEL GROUND TABS, LED SIZE CAGE CODE DRAWING NO. RESTRICTED TO A100779C=1116132	
CUSTOMER DRAWING				SCALE 4:1		SHEET 1 OF 1 REV C1	